



DYNAMIC SOLUTIONS THE LINK TO BRIDGING CONCEPTS



AUD
Advanced Ultra Desorber

- Eliminates remaining moisture after Pod Cleaning*
- Eliminates AMC such as VOC in carrier environment*
- Pods are ready to use after AUD process*
- Real Time Desorption Monitoring**
- Allows reproductive conditioning of the pods*
- Simplify Pod Management*

AUD Advanced Ultra Desorber FOUP/FOSB Decontamination System



M 300 Milestone
FOUP/ FOSB Cleaner

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Dynamic Micro Systems

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International Technology Roadmap:

- Smaller particle sizes will have to be eliminated as the device dimensions decreased
- Particle down to 0.1um and Metal contamination that are collected during the fab process are being collected on wafer and wafer carrier.
- FOUP have to be kept very clean which requires frequent cleaning.

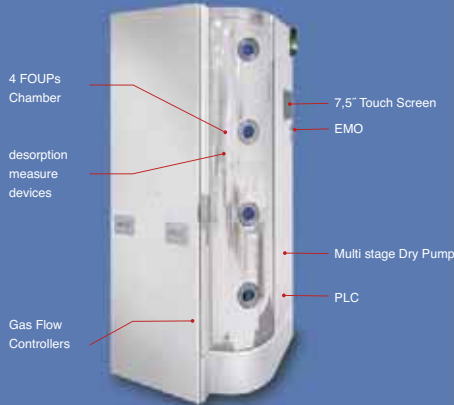


AUD Advanced Ultra Desorber

FOUP/FOSB Decontamination System

System Advantages:

After FOUP/ FOSB have been cleaned in M300 Centrifugal Force Cleaner the FOUP/ FOSB can be placed inside of the AUD for final drying and decontamination process (eliminates AMC outgasing)

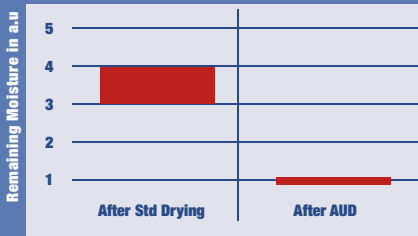


The system's functionality:

- It eliminates Pod AMC and moisture using desorption process
- 4 FOUP capacity, other pod configurations available
- Simultaneous Desorption of FOUP units and doors
- Integrated Real Time Desorption Monitoring*



Results with AUD on Moisture removal



Comparison between standard drying and AUD process on FOUP remaining moisture level: 20mn AUD process allows 3 times better FOUP conditioning level & uniformity



Facility Requirements

- Dimensions (H x L x D): 2100 x 800x 900 mm
- Electrical power supply: 100-240 Vac 50-60 Hz / 15A-6.5A / 1.5 kW (max.)
- Purified XCDA (process): 5 Bar to 10 bar
- XCDA connection: inch tube
- Process exhaust: NW40 isoKF
- Operating temperature: 20 – 25 °C
- Humidity: 30 – 50% HR
- Operating area: Clean room (up to 10000 class)
- Noise level: < 55 dBA
- Weight: ~350 kg
- XCDA consumption: <300 NL/cycle
- Operation Cycle time: 30 to 60 min

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